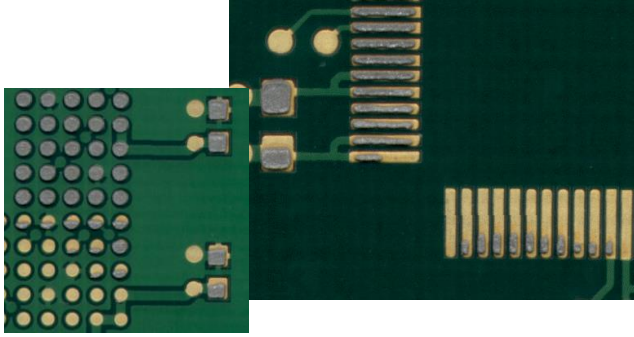


# ScanINSPECT SPI™

## Solder Paste Inspection



### WHAT IS ScanINSPECT SPI?

ScanINSPECT SPI provides a simple and user-friendly alternative to inaccurate and time-consuming manual inspection methods or expensive, high-end AOI systems.

ScanINSPECT SPI uses a simple Windows user interface integrated with a manual load table and image-processing unit. This combination allows 100% inspection of printed solder paste.

### HOW DOES ScanINSPECT SPI WORK?

ScanINSPECT SPI provides 100% 2D non-contact verification of bridging, paste on pads, and the total area of solder paste before adding further value to the PCB.

Provides offline inspection for low volume production or SPC sampling for high volume production.

Each part or substrate is placed from the printing machine into ScanINSPECT SPI for 100% inspection. The part is then accepted and continues on with the process or rejected for disposition. No more surprises!

### QUICK & SIMPLE PROGRAMMING

ScanINSPECT SPI is quickly programmed from a golden part in a few minutes.

### INCREASE YIELD & IMPROVE OVERALL EQUIPMENT EFFICIENCY

ScanINSPECT SPI's powerful inspection process increases product yield by ensuring accurate solder paste printing, thus, assisting with high yields and minimal rework and/or scrap.

Missing or defective solder paste can result in lost production time and extensive rework. SPI eliminates operator fatigue and tedium from the inspection task, and automatically verifies 100% of the paste.

Missing, paste off pad, bridging, and over/under print area solder paste defects are now automatically detected. Problems are found and eliminated before value is added to defective parts.

### SIMPLICITY

ScanINSPECT SPI set up is fast and easy. In production, each board is placed on the table, shuttled in, automatically aligned and checked for accuracy with a PASS or FAIL inspection in seconds. Failures are detected, logged and printed for easy analysis or rework.

### WHY USE ScanINSPECT SPI?

- **Mandatory:** 100% automatic inspection of solder paste.
- **Security:** Confirm solder paste on pads, total area of the paste, and detect bridging.
- **Necessity:** Detect errors before adding further value to defective parts.
- **Flexibility:** Inspect a wide variety of part sizes and shapes.



### DESKTOP MODULE

#### System Specifications\*

- Maximum Assembly Size: 18" X 24" (457mm X 610mm)
- Maximum Inspection Area: 16.5" X 22" (419mm X 559mm)
- Resolution: Range from 200 to 2400 dpi

#### Footprint of Inspection Unit

- Depth: 31.5" (800mm), table extended 49.5" (1,257mm)
- Width: 27.25" (692mm)
- Height: 19" (482mm)
- Weight: 150lbs. (55.95kg)

#### COMPUTER\*

- Multi Core Processor - 3 GHz
- 1 TB 7200 RPM HD, 8 - 16 GB RAM
- Flat Panel Monitor
- Ethernet Connection
- Windows 10 - 64-Bit
- 2 avail. USB2 or USB3 ports

\*Recommended customer-supplied minimum PC requirements.

**(All specifications and designs subject to change without notice.)**

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